

SN74AHCT1G125 具有三态输出的单路总线缓冲门

1 特性

- 工作电压范围为 4.5V 至 5.5V
- 电压为 5V 时, t_{pd} 最大值为 6ns
- 低功耗, I_{CC} 最大值为 10 μ A
- 电压为 5V 时, 输出驱动为 ± 8 mA
- 输入兼容 TTL 电压
- 闩锁性能超过 250mA, 符合 JESD 17 规范

2 应用

- 无线基础设施
- 服务器
- 电力基础设施
- PC/笔记本电脑
- 可编程逻辑控制器
- 测试和测量

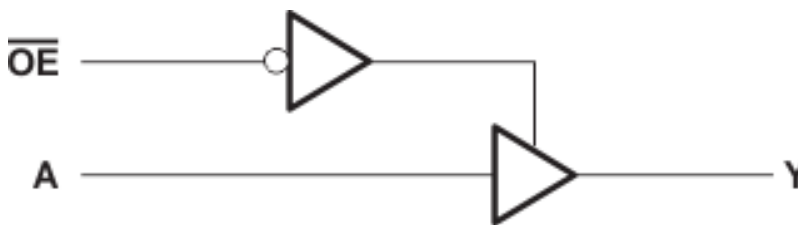
3 说明

SN74AHCT1G125 器件是一款具有三态输出的单通道总线缓冲门/线路驱动器。当输出使能 ($\overline{OE}$) 输入为高电平时, 输出被禁用。当 $\overline{OE}$ 为低电平时, 数据从 A 输入传递到 Y 输出。

封装信息

器件型号	封装 ⁽¹⁾	封装尺寸 ⁽²⁾	本体尺寸 ⁽³⁾
SN74AHCT1G125	DBV (SOT-23 , 5)	2.9mm x 2.8mm	2.9mm x 1.6mm
	DCK (SC-70 , 5)	2mm x 2.1mm	2mm x 1.25mm
	DRL (SOT-553 , 5)	1.6mm x 1.6mm	1.6mm x 1.2mm

- 如需了解更多信息, 请参阅第 11 节。
- 封装尺寸 (长 × 宽) 为标称值, 并包括引脚 (如适用)。
- 本体尺寸 (长 × 宽) 为标称值, 不包括引脚。



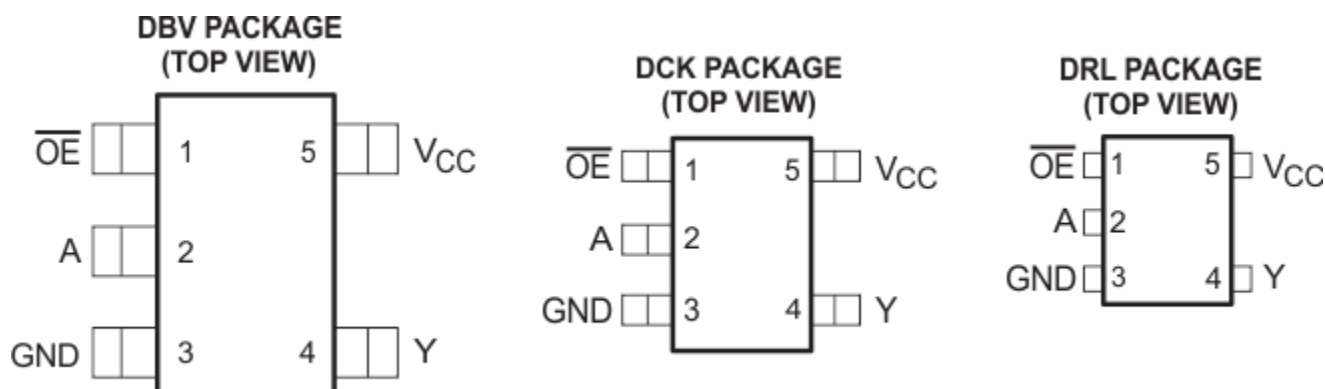
简化原理图



Table of Contents

1 特性	1	7.3 Feature Description.....	8
2 应用	1	7.4 Device Functional Modes.....	8
3 说明	1	8 Application and Implementation	9
4 Pin Configuration and Functions	3	8.1 Application Information.....	9
5 Specifications	4	8.2 Typical Application.....	9
5.1 Absolute Maximum Ratings.....	4	8.3 Power Supply Recommendations.....	10
5.2 ESD Ratings.....	4	8.4 Layout.....	10
5.3 Recommended Operating Conditions.....	4	9 Device and Documentation Support	12
5.4 Thermal Information.....	5	9.1 接收文档更新通知.....	12
5.5 Electrical Characteristics.....	5	9.2 支持资源.....	12
5.6 Switching Characteristics.....	6	9.3 Trademarks.....	12
5.7 Operating Characteristics.....	6	9.4 静电放电警告.....	12
5.8 Typical Characteristics.....	6	9.5 术语表.....	12
6 Parameter Measurement Information	7	10 Revision History	12
7 Detailed Description	8	11 Mechanical, Packaging, and Orderable Information	12
7.1 Overview.....	8		
7.2 Functional Block Diagram.....	8		

4 Pin Configuration and Functions



See mechanical drawings for dimensions.

表 4-1. Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NO.	NAME		
1	$\overline{OE}$	I	Output Enable
2	A	I	Input A
3	GND	—	Ground Pin
4	Y	O	Output Y
5	V_{CC}	—	Power Pin

(1) Signal Types: I = Input, O = Output, I/O = Input or Output

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	- 0.5	7	V
V_I ⁽²⁾	Input voltage range	- 0.5	7	V
V_O ⁽²⁾	Output voltage range	- 0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$	- 20	mA
I_{OK}	Output clamp current	$V_O < 0$ or $V_O > V_{CC}$	±20	mA
I_O	Continuous output current	$V_O = 0$ to V_{CC}	±25	mA
	Continuous channel current through V_{CC} or GND		±50	mA
T_{stg}	Storage temperature range	- 65	150	°C
T_J	Junction temperature		150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under [§ 5.3](#) is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	±1000
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾	±1500

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage	4.5	5.5	V
V_{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		0.8	V
V_I	Input voltage	0	5.5	V
V_O	Output voltage	0	V_{CC}	V
I_{OH}	High-level output current		- 8	mA
I_{OL}	Low-level output current		8	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		20	ns/V
T_A	Operating free-air temperature	- 40	125	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs* ([SCBA004](#)).

5.4 Thermal Information

THERMAL METRIC ⁽¹⁾		DBV	DCK	DRL	UNIT
		5 PINS			
R _{θ JA}	Junction-to-ambient thermal resistance	278	289.2	328.7	°C/W
R _{θ JC(top)}	Junction-to-case (top) thermal resistance	180.5	205.8	105.1	
R _{θ JB}	Junction-to-board thermal resistance	184.4	176.2	150.3	
ψ _{JT}	Junction-to-top characterization parameter	115.4	117.6	6.9	
ψ _{JB}	Junction-to-board characterization parameter	183.4	175.1	148.4	
R _{θ JC(bot)}	Junction-to-case (bot) thermal resistance	N/A	N/A	N/A	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report (SPRA953).

5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	$T_A = 25^\circ\text{C}$			$-40^\circ\text{C to } 85^\circ\text{C}$		$-40^\circ\text{C to } 125^\circ\text{C}$		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH} High level output voltage	$I_{OH} = -50\ \mu\text{A}$	4.5 V	4.4	4.5		4.4		4.4		V
	$I_{OH} = -8\ \text{mA}$		3.94			3.8		3.8		
V_{OL} Low level output voltage	$I_{OL} = 50\ \mu\text{A}$	4.5 V			0.1		0.1		0.1	V
	$I_{OL} = 8\ \text{mA}$				0.36		0.44		0.44	
I_I Input leakage current	$V_I = 5.5\ \text{V or GND}$	0 V to 5.5 V			± 0.1		± 1		± 1	μA
I_{OZ} Off-State (High-Impedance State) Output Current (of a 3-State Output)	$V_O = V_{CC}\ \text{or GND}$	5.5 V			± 0.25		± 2.5		± 2.5	μA
I_{CC} Supply current	$V_I = V_{CC}\ \text{or GND, } I_O = 0$	5.5 V			1		10		10	μA
ΔI_{CC} ⁽¹⁾ Supply-current change	One input at 3.4 V, Other input at V_{CC} or GND	5.5 V			1.35		1.5		1.5	mA
C_i Input capacitance	$V_I = V_{CC}\ \text{or GND}$	5 V		4	10		10		10	pF
C_o Output capacitance	$V_O = V_{CC}\ \text{or GND}$	5 V		10						pF

(1) This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V_{CC} .

5.6 Switching Characteristics

over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			$-40^\circ\text{C to } 85^\circ\text{C}$		$-40^\circ\text{C to } 125^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	$C_L = 15\text{ pF}$		3.8	5.5	1	6.5	1	7	ns
t_{PHL}					3.8	5.5	1	6.5	1	7	
t_{PZH}	$\overline{OE}$	Y	$C_L = 15\text{ pF}$		3.6	5.1	1	6	1	6.5	ns
t_{PZL}					3.6	5.1	1	6	1	6.5	
t_{PHZ}	$\overline{OE}$	Y	$C_L = 15\text{ pF}$		4.6	6.8	1	8	1	8.5	ns
t_{PLZ}					4.6	6.8	1	8	1	8.5	
t_{PLH}	A	Y	$C_L = 50\text{ pF}$		5.3	7.5	1	8.5	1	9.5	ns
t_{PHL}					5.3	7.5	1	8.5	1	9.5	
t_{PZH}	$\overline{OE}$	Y	$C_L = 50\text{ pF}$		5.1	7.1	1	8	1	9	ns
t_{PZL}					5.1	7.1	1	8	1	9	
t_{PHZ}	$\overline{OE}$	Y	$C_L = 50\text{ pF}$		6.1	8.8	1	10	1	11	ns
t_{PLZ}					6.1	8.8	1	10	1	11	

5.7 Operating Characteristics

$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	No load,	$f = 1\text{ MHz}$	14	pF

5.8 Typical Characteristics

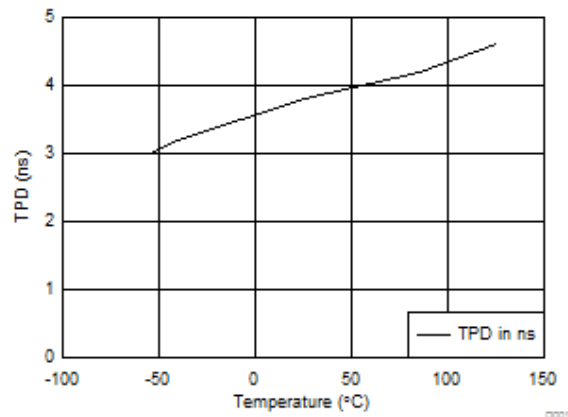
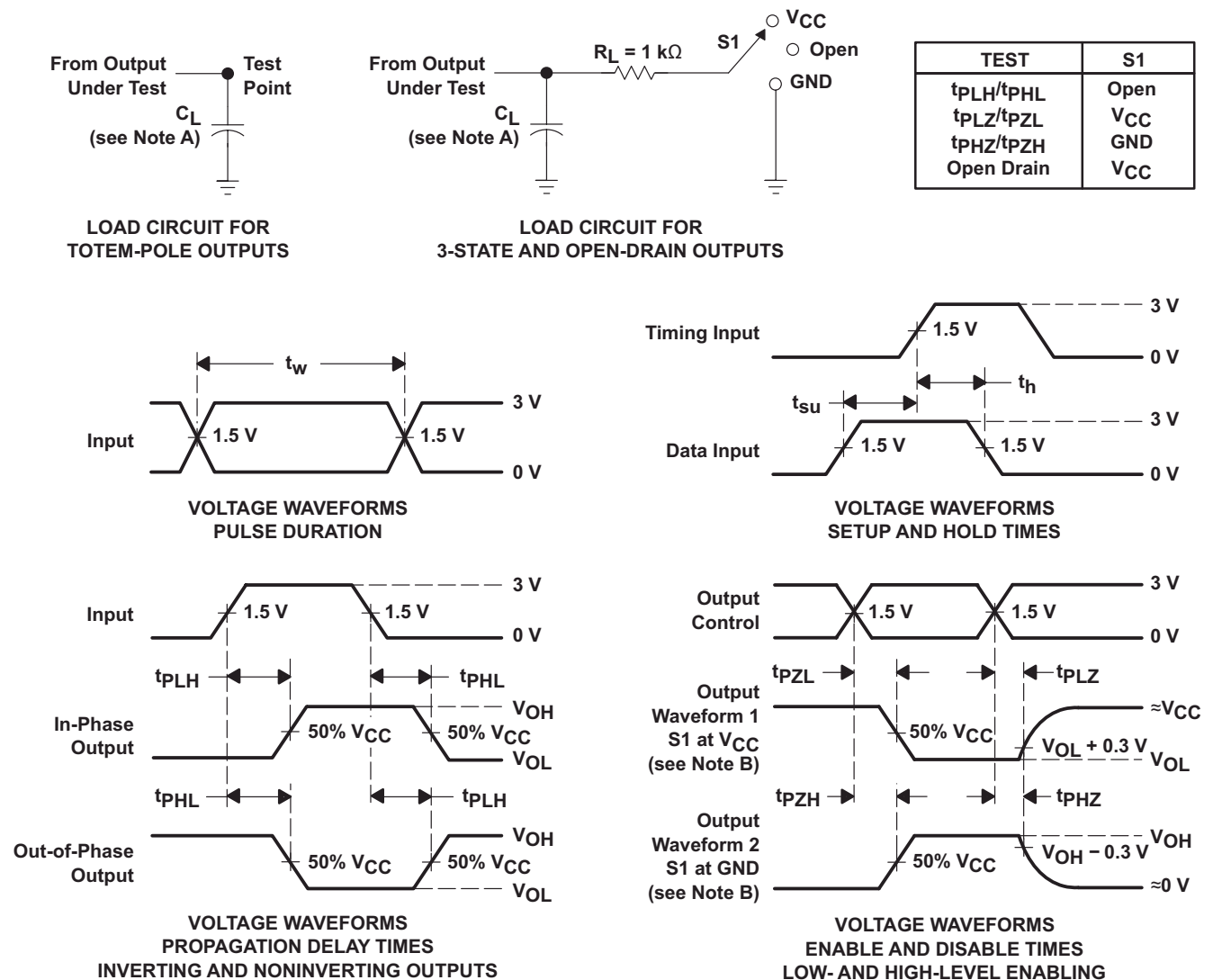


图 5-1. TPD vs Temperature

6 Parameter Measurement Information



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 - D. The outputs are measured one at a time, with one input transition per measurement.
 - E. All parameters and waveforms are not applicable to all devices.

图 6-1. Load Circuit and Voltage Waveforms

7 Detailed Description

7.1 Overview

The SN74AHCT1G125 device is a single bus buffer gate/line driver with 3-state output. The output is disabled when the output-enable ($\overline{OE}$) input is high. When $\overline{OE}$ is low, data is passed from the A input to the Y output.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

7.2 Functional Block Diagram

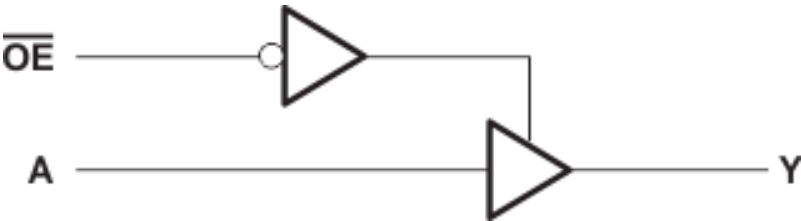


图 7-1. Logic Diagram (Positive Logic)

7.3 Feature Description

- TTL inputs
 - Lowered switching threshold allows up translation 3.3 V to 5 V
- Slow edges reduce output ringing

7.4 Device Functional Modes

表 7-1. Function Table

INPUTS ⁽¹⁾		OUTPUT ⁽²⁾
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

- (1) H = High Voltage Level, L = Low Voltage Level, X = Don' t Care
- (2) H = Driving High, L = Driving Low, Z = High Impedance State

8 Application and Implementation

备注

以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

8.1 Application Information

The SN74AHCT1G125 is a low-drive CMOS device that can be used for a multitude of bus interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The input switching levels have been lowered to accommodate TTL inputs of 0.8 V_{IL} and 2 V_{IH} . This feature makes it ideal for translating up from 3.3 V to 5 V . 图 8-1 shows this type of translation.

8.2 Typical Application

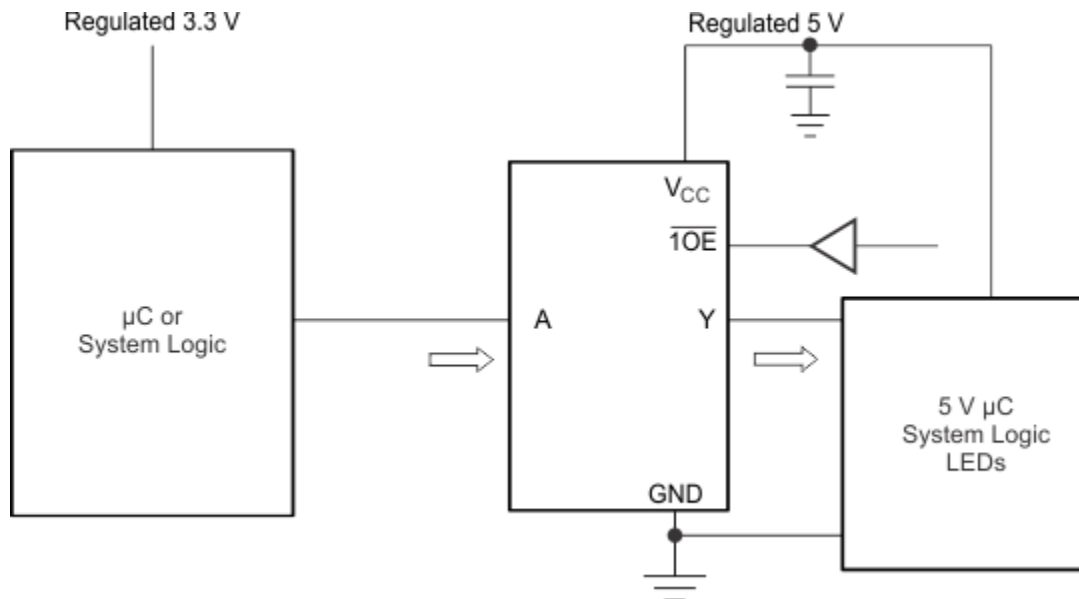


图 8-1. Typical Application Schematic

8.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads, so routing and load conditions should be considered to prevent ringing.

8.2.2 Detailed Design Procedure

- Recommended Input Conditions
 - For rise time and fall time specifications, see $\Delta t / \Delta V$ in the 节 5.3 table.
 - For specified High and low levels, see V_{IH} and V_{IL} in the 节 5.3 table.
 - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid V_{CC} .
- Recommend Output Conditions
 - Load currents should not exceed 25 mA per output and 50 mA total for the part.
 - Outputs should not be pulled above V_{CC} .

8.2.3 Application Curves

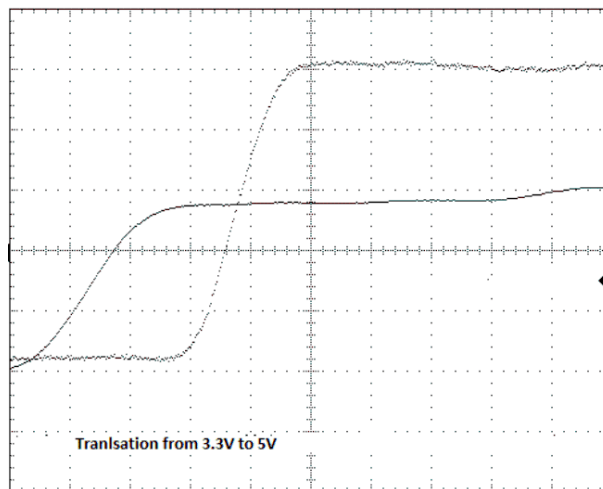


图 8-2. Translation from 3.3 V to 5 V

8.3 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the [节 5.3](#) table.

Each V_{CC} pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1 μF is recommended. If there are multiple V_{CC} pins, 0.01 μF or 0.022 μF is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1 μF and 1 μF are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

8.4 Layout

8.4.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in [图 8-3](#) are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} , whichever makes more sense or is more convenient. It is acceptable to float outputs unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the outputs section of the part when asserted. This will not disable the input section of the I/Os so they also cannot float when disabled.

8.4.1.1 Layout Example

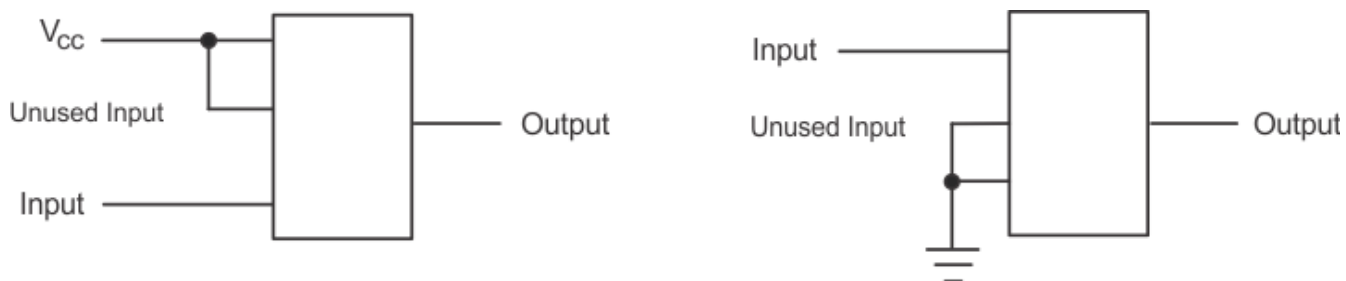


图 8-3. Layout Diagram

9 Device and Documentation Support

9.1 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 [通知](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

9.2 支持资源

TI E2E™ 中文支持论坛是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的[使用条款](#)。

9.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

所有商标均为其各自所有者的财产。

9.4 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

9.5 术语表

TI 术语表 本术语表列出并解释了术语、首字母缩略词和定义。

10 Revision History

Changes from Revision O (October 2023) to Revision P (March 2024)	Page
• 向 封装信息 表中添加了本体尺寸.....	1
• Updated thermal values for DBV package from R _θ JA = 231.3 to 278, R _θ JC(top) = 119.9 to 180.5, R _θ JB = 60.6 to 184.4, Ψ JT = 17.8 to 115.4, Ψ JB = 60.1 to 183.4, R _θ JC(bot) = N/A, all values in °C/W	5

Changes from Revision N (January 2016) to Revision O (October 2023)	Page
• 更新了整个文档中的表格、图和交叉参考的编号格式.....	1
• Updated thermal values for DCK package from R _θ JA = 287.6 to 289.2, R _θ JC(top) = 97.7 to 205.8, R _θ JB = 65 to 176.2, Ψ JT = 2.0 to 117.6, Ψ JB = 64.2 to 175.1, R _θ JC(bot) = N/A, all values in °C/W	5

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
74AHCT1G125DBVRG4	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	B25G
74AHCT1G125DBVRG4.A	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	B25G
74AHCT1G125DBVTG4	Active	Production	SOT-23 (DBV) 5	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	B25G
74AHCT1G125DBVTG4.A	Active	Production	SOT-23 (DBV) 5	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	B25G
74AHCT1G125DCKRG4	Active	Production	SC70 (DCK) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	BM3
74AHCT1G125DCKRG4.A	Active	Production	SC70 (DCK) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	BM3
74AHCT1G125DCKTE4	Active	Production	SC70 (DCK) 5	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	BM3
74AHCT1G125DCKTG4	Active	Production	SC70 (DCK) 5	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	BM3
74AHCT1G125DCKTG4.A	Active	Production	SC70 (DCK) 5	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	BM3
SN74AHCT1G125DBVR	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	Call TI Sn	Level-1-260C-UNLIM	-40 to 125	(37QH, 3BEF, B253, B25G, B25J, B25L, B25S)
SN74AHCT1G125DBVR.A	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	(37QH, 3BEF, B253, B25G, B25J, B25L, B25S)
SN74AHCT1G125DBVT	Obsolete	Production	SOT-23 (DBV) 5	-	-	Call TI	Call TI	-40 to 125	(B253, B25G, B25J, B25S)
SN74AHCT1G125DCK3	Last Time Buy	Production	SC70 (DCK) 5	3000 LARGE T&R	Yes	SNBI	Level-1-260C-UNLIM	-40 to 85	BMJ
SN74AHCT1G125DCK3.A	Last Time Buy	Production	SC70 (DCK) 5	3000 LARGE T&R	Yes	SNBI	Level-1-260C-UNLIM	-40 to 85	BMJ
SN74AHCT1G125DCKR	Active	Production	SC70 (DCK) 5	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	(1QK, BM3, BMG, BMJ, BML, BMS)
SN74AHCT1G125DCKR.A	Active	Production	SC70 (DCK) 5	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	(1QK, BM3, BMG, BMJ, BML, BMS)
SN74AHCT1G125DCKT	Obsolete	Production	SC70 (DCK) 5	-	-	Call TI	Call TI	-40 to 125	(BM3, BMG, BMJ, BMS)
SN74AHCT1G125DRLR	Active	Production	SOT-5X3 (DRL) 5	4000 LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	(BMB, BMS)
SN74AHCT1G125DRLR.A	Active	Production	SOT-5X3 (DRL) 5	4000 LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	(BMB, BMS)

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

(2) Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) RoHS values: Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

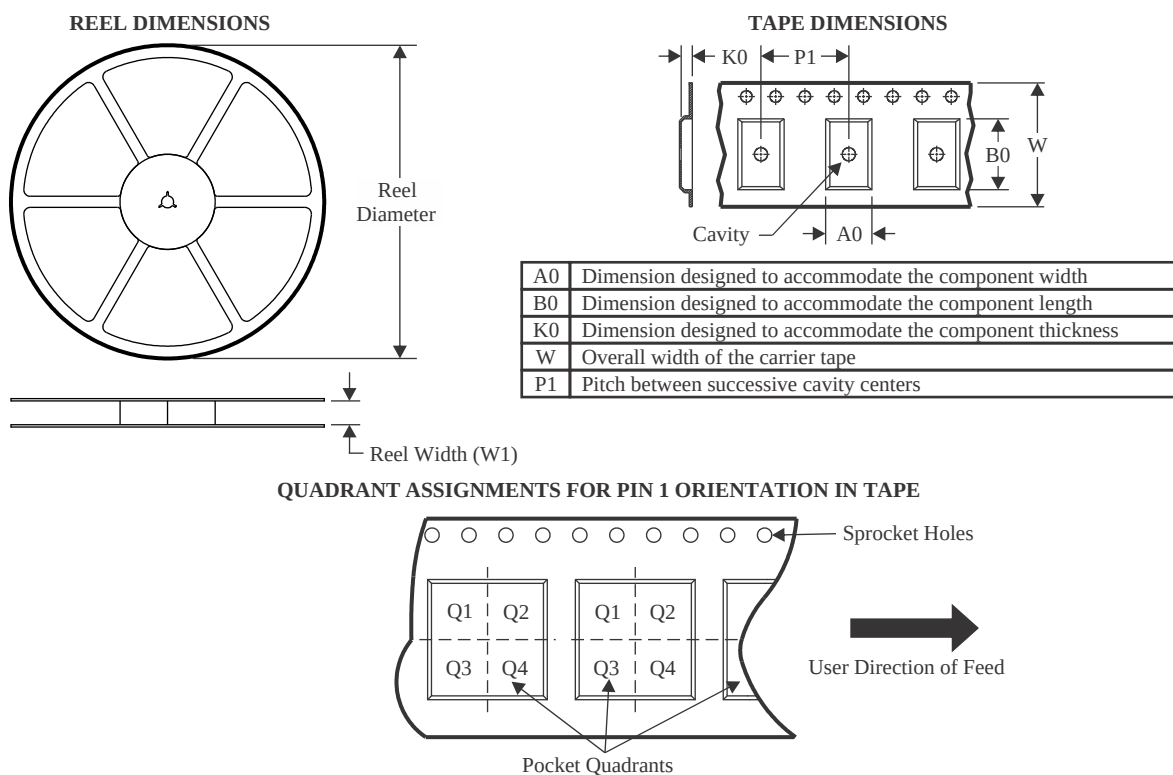
OTHER QUALIFIED VERSIONS OF SN74AHCT1G125 :

- Automotive : [SN74AHCT1G125-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

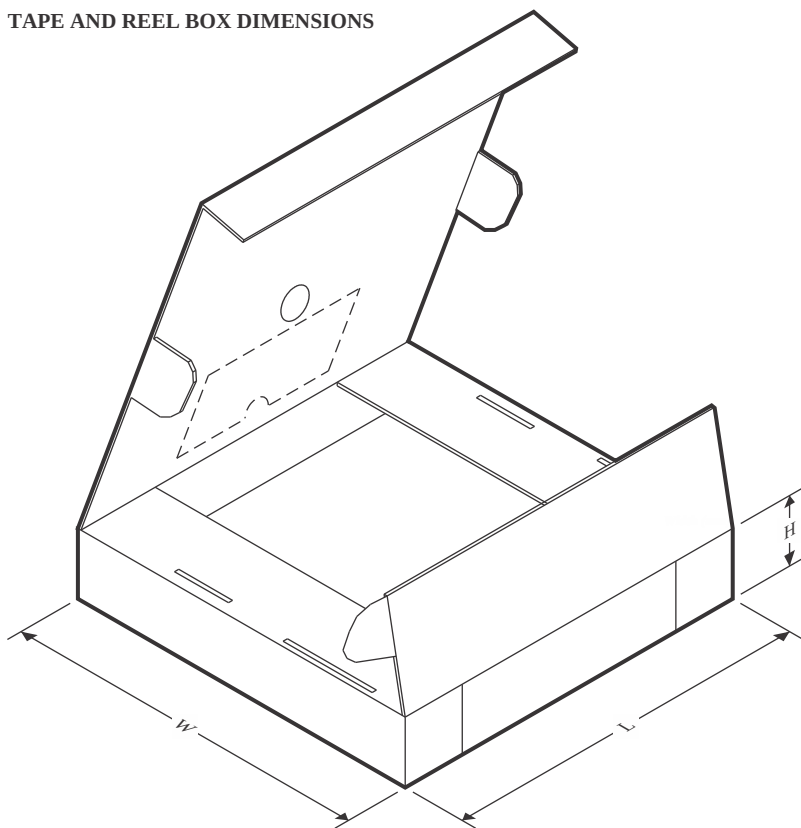
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74AHCT1G125DBVRG4	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
74AHCT1G125DBVTG4	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
74AHCT1G125DCKRG4	SC70	DCK	5	3000	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
74AHCT1G125DCKTG4	SC70	DCK	5	250	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74AHCT1G125DBVR	SOT-23	DBV	5	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
SN74AHCT1G125DBVR	SOT-23	DBV	5	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
SN74AHCT1G125DBVR	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
SN74AHCT1G125DCKR	SC70	DCK	5	3000	180.0	8.4	2.3	2.55	1.2	4.0	8.0	Q3
SN74AHCT1G125DRLR	SOT-5X3	DRL	5	4000	180.0	8.4	1.98	1.78	0.69	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74AHCT1G125DBVRG4	SOT-23	DBV	5	3000	180.0	180.0	18.0
74AHCT1G125DBVTG4	SOT-23	DBV	5	250	180.0	180.0	18.0
74AHCT1G125DCKRG4	SC70	DCK	5	3000	180.0	180.0	18.0
74AHCT1G125DCKTG4	SC70	DCK	5	250	180.0	180.0	18.0
SN74AHCT1G125DBVR	SOT-23	DBV	5	3000	210.0	185.0	35.0
SN74AHCT1G125DBVR	SOT-23	DBV	5	3000	210.0	185.0	35.0
SN74AHCT1G125DBVR	SOT-23	DBV	5	3000	208.0	191.0	35.0
SN74AHCT1G125DCKR	SC70	DCK	5	3000	210.0	185.0	35.0
SN74AHCT1G125DRLR	SOT-5X3	DRL	5	4000	202.0	201.0	28.0



SOT - 0.6 mm max height

Technical drawing of a 5-pin D-subminiature connector housing, showing front, side, and top views with dimensions and feature callouts.

Front View (Top):

- Overall width: 1.7
- Overall height: 1.7
- Pin 1 ID Area: Indicated by a dashed line and label.
- Pin 1: Located at the top left.
- Pin 2: Located at the top right.
- Pin 3: Located at the bottom left.
- Pin 4: Located at the bottom right.
- Pin 5: Located at the top center.
- Feature A: Located at the top right corner.
- Feature B: Located at the bottom left corner.
- Feature C: Located at the bottom right corner.
- Feature D: Located at the bottom left corner.
- Feature E: Located at the bottom right corner.
- Feature F: Located at the bottom center.
- Feature G: Located at the bottom center.
- Feature H: Located at the bottom center.
- Feature I: Located at the bottom center.
- Feature J: Located at the bottom center.
- Feature K: Located at the bottom center.
- Feature L: Located at the bottom center.
- Feature M: Located at the bottom center.
- Feature N: Located at the bottom center.
- Feature O: Located at the bottom center.
- Feature P: Located at the bottom center.
- Feature Q: Located at the bottom center.
- Feature R: Located at the bottom center.
- Feature S: Located at the bottom center.
- Feature T: Located at the bottom center.
- Feature U: Located at the bottom center.
- Feature V: Located at the bottom center.
- Feature W: Located at the bottom center.
- Feature X: Located at the bottom center.
- Feature Y: Located at the bottom center.
- Feature Z: Located at the bottom center.

Side View (Middle):

- Overall width: 1.3
- Overall height: 1.1
- Feature A: Located at the top right corner.
- Feature B: Located at the bottom left corner.
- Feature C: Located at the bottom right corner.
- Feature D: Located at the bottom left corner.
- Feature E: Located at the bottom right corner.
- Feature F: Located at the bottom center.
- Feature G: Located at the bottom center.
- Feature H: Located at the bottom center.
- Feature I: Located at the bottom center.
- Feature J: Located at the bottom center.
- Feature K: Located at the bottom center.
- Feature L: Located at the bottom center.
- Feature M: Located at the bottom center.
- Feature N: Located at the bottom center.
- Feature O: Located at the bottom center.
- Feature P: Located at the bottom center.
- Feature Q: Located at the bottom center.
- Feature R: Located at the bottom center.
- Feature S: Located at the bottom center.
- Feature T: Located at the bottom center.
- Feature U: Located at the bottom center.
- Feature V: Located at the bottom center.
- Feature W: Located at the bottom center.
- Feature X: Located at the bottom center.
- Feature Y: Located at the bottom center.
- Feature Z: Located at the bottom center.

Top View (Bottom):

- Overall width: 1.3
- Overall height: 1.1
- Feature A: Located at the top right corner.
- Feature B: Located at the bottom left corner.
- Feature C: Located at the bottom right corner.
- Feature D: Located at the bottom left corner.
- Feature E: Located at the bottom right corner.
- Feature F: Located at the bottom center.
- Feature G: Located at the bottom center.
- Feature H: Located at the bottom center.
- Feature I: Located at the bottom center.
- Feature J: Located at the bottom center.
- Feature K: Located at the bottom center.
- Feature L: Located at the bottom center.
- Feature M: Located at the bottom center.
- Feature N: Located at the bottom center.
- Feature O: Located at the bottom center.
- Feature P: Located at the bottom center.
- Feature Q: Located at the bottom center.
- Feature R: Located at the bottom center.
- Feature S: Located at the bottom center.
- Feature T: Located at the bottom center.
- Feature U: Located at the bottom center.
- Feature V: Located at the bottom center.
- Feature W: Located at the bottom center.
- Feature X: Located at the bottom center.
- Feature Y: Located at the bottom center.
- Feature Z: Located at the bottom center.

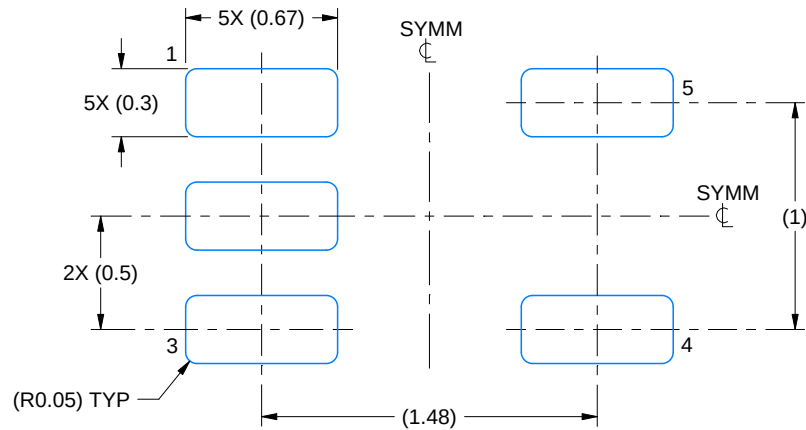
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-293 Variation UAAD-1

EXAMPLE BOARD LAYOUT

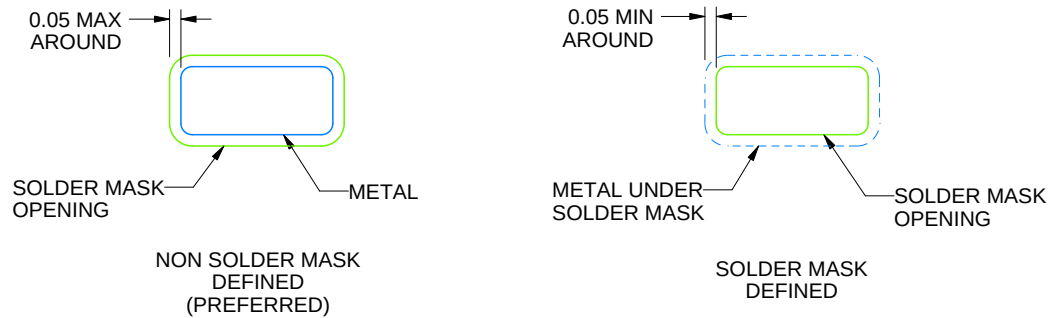
DRL0005A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE
SCALE:30X



SOLDERMASK DETAILS

4220753/E 11/2024

NOTES: (continued)

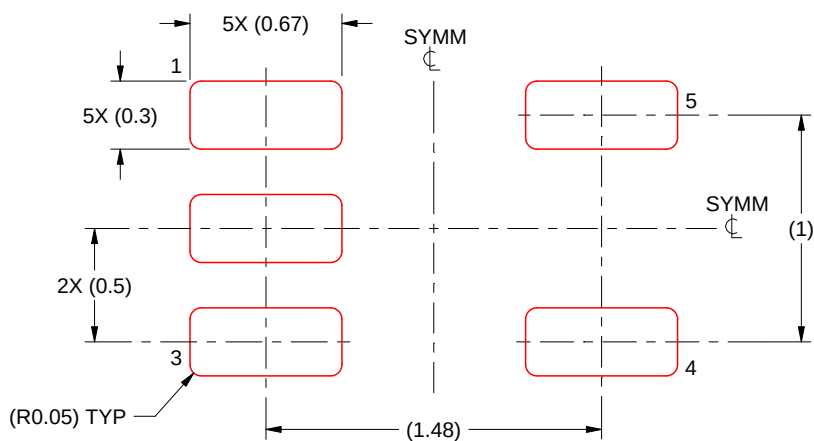
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DRL0005A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE

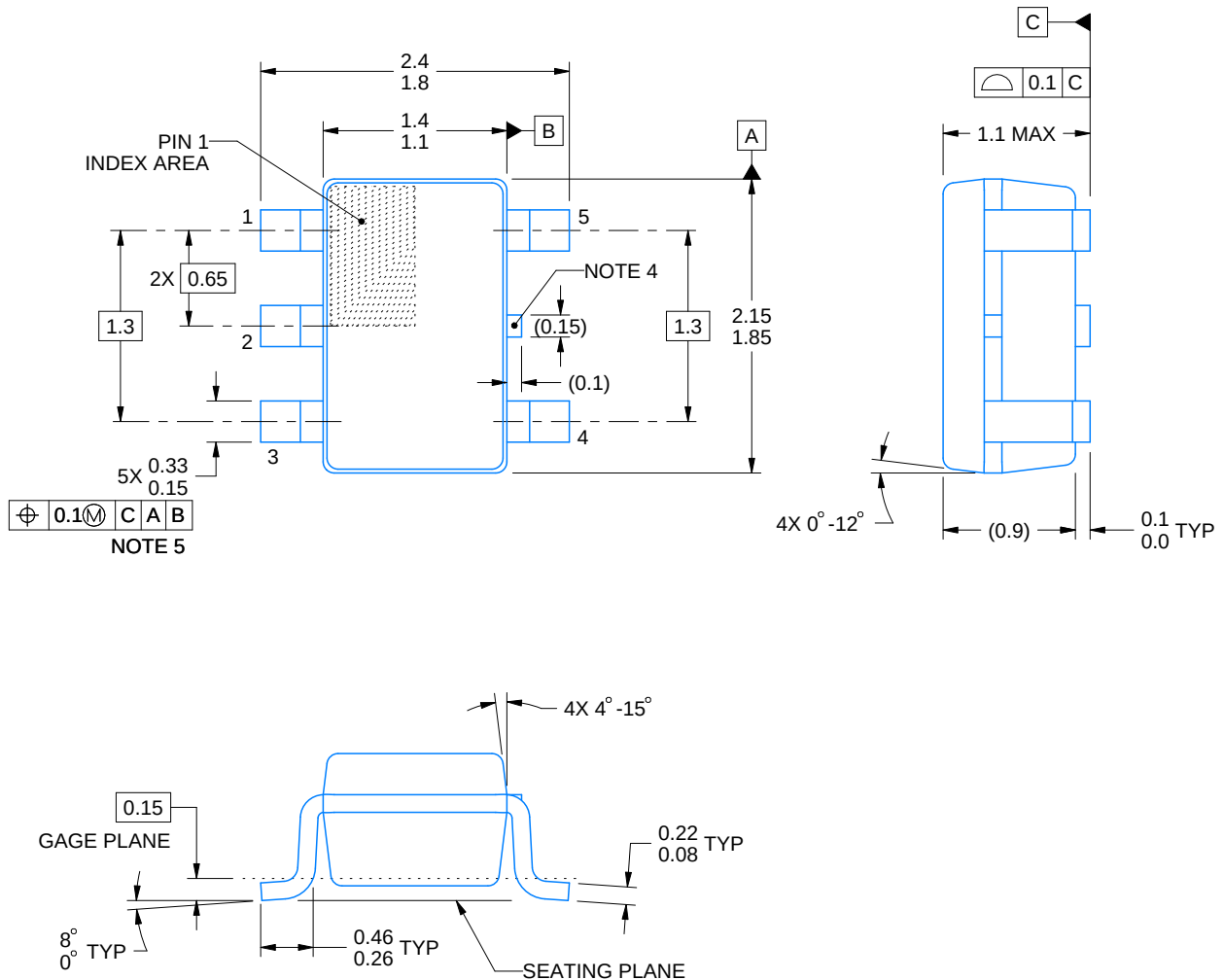


SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:30X

4220753/E 11/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.



4214834/G 11/2024

NOTES:

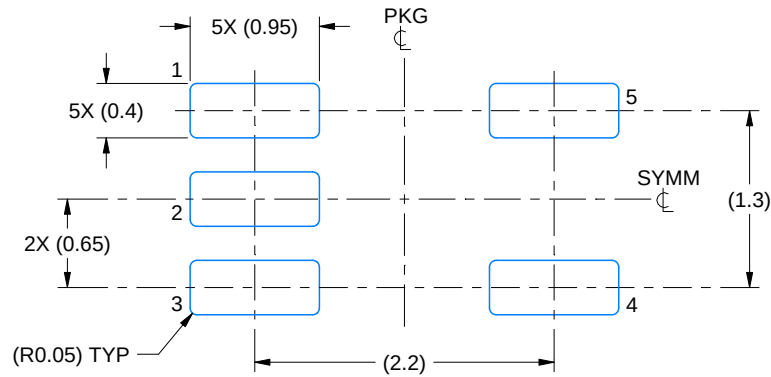
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-203.
4. Support pin may differ or may not be present.
5. Lead width does not comply with JEDEC.
6. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side

EXAMPLE BOARD LAYOUT

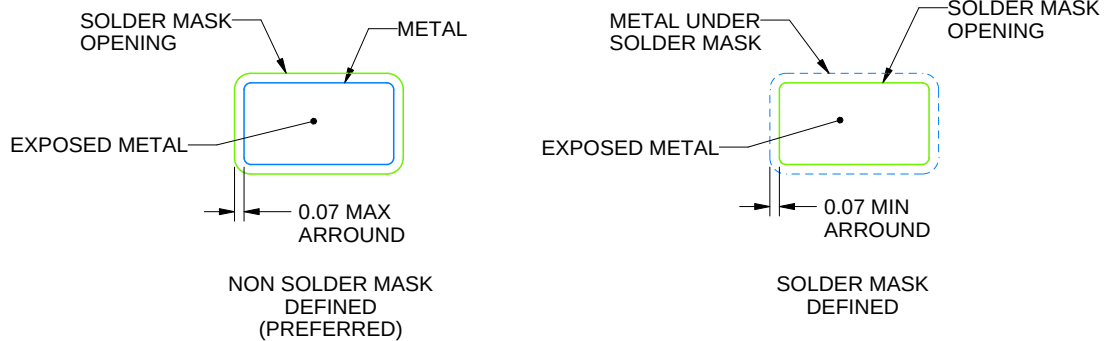
DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X

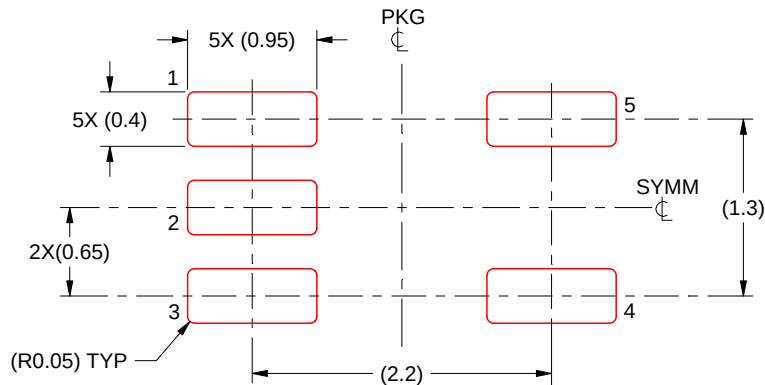


SOLDER MASK DETAILS

4214834/G 11/2024

NOTES: (continued)

7. Publication IPC-7351 may have alternate designs.
8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:18X

4214834/G 11/2024

NOTES: (continued)

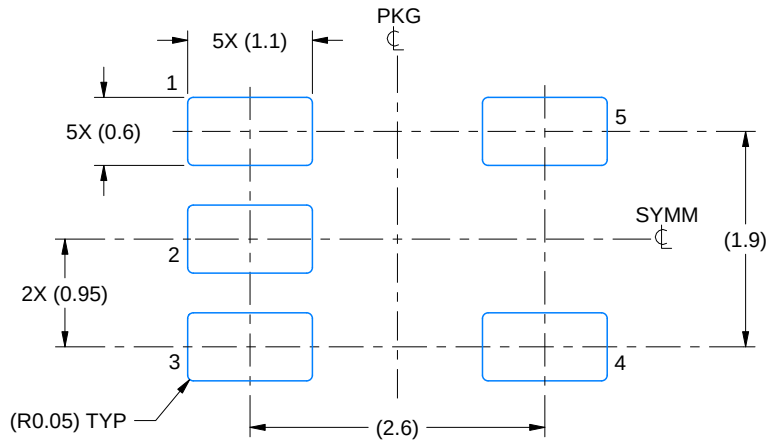
9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
10. Board assembly site may have different recommendations for stencil design.

EXAMPLE BOARD LAYOUT

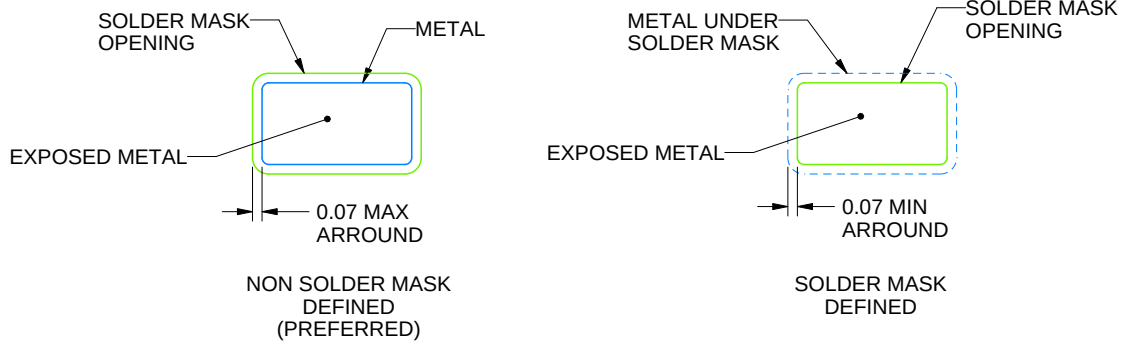
DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

4214839/K 08/2024

NOTES: (continued)

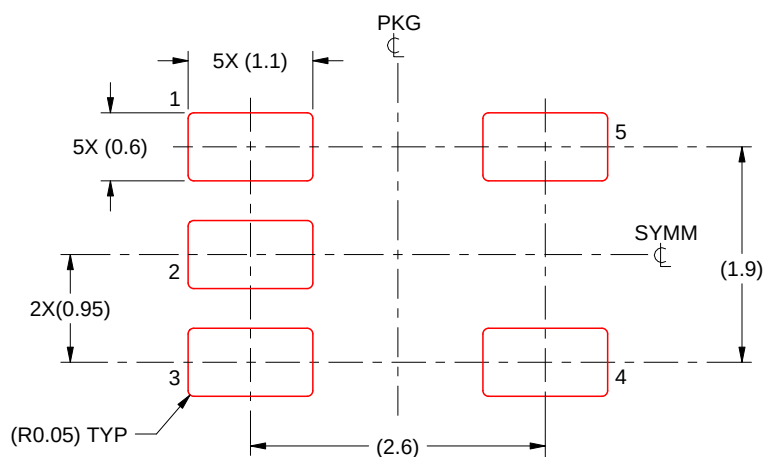
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214839/K 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要通知和免责声明

TI“按原样”提供技术和可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证没有瑕疵且不做任何明示或暗示的担保，包括但不限于对适销性、与某特定用途的适用性或不侵犯任何第三方知识产权的暗示担保。

这些资源可供使用 TI 产品进行设计的熟练开发人员使用。您将自行承担以下全部责任：(1) 针对您的应用选择合适的 TI 产品，(2) 设计、验证并测试您的应用，(3) 确保您的应用满足相应标准以及任何其他安全、安保法规或其他要求。

这些资源如有变更，恕不另行通知。TI 授权您仅可将这些资源用于研发本资源所述的 TI 产品的相关应用。严禁以其他方式对这些资源进行复制或展示。您无权使用任何其他 TI 知识产权或任何第三方知识产权。对于因您对这些资源的使用而对 TI 及其代表造成的任何索赔、损害、成本、损失和债务，您将全额赔偿，TI 对此概不负责。

TI 提供的产品受 [TI 销售条款](#)、[TI 通用质量指南](#) 或 [ti.com](#) 上其他适用条款或 TI 产品随附的其他适用条款的约束。TI 提供这些资源并不会扩展或以其他方式更改 TI 针对 TI 产品发布的适用的担保或担保免责声明。除非德州仪器 (TI) 明确将某产品指定为定制产品或客户特定产品，否则其产品均为按确定价格收入目录的标准通用器件。

TI 反对并拒绝您可能提出的任何其他或不同的条款。

版权所有 © 2026，德州仪器 (TI) 公司

最后更新日期：2025 年 10 月